ON Semiconductor®

FSA3051 —High Performance SPDT Analog Switch with Over-Voltage Tolerance

Features

- Low On Capacitance: 7.7 pF Typical
- Low On Resistance: 6 Ω Typical
- Low Power Consumption: 1 µA Maximum
  - 15 µA Maximum I_{CCT} over an Expanded Voltage Range (V_{IN}=1.8 V, V_{CC}=5.5 V)
- Wide -3 db Bandwidth: 1.0 GHz
- Packaged in Ultra Small 6-Lead TMLP
- Broad V_{CC} Operating Range: 1.6 V to 5.5 V
- Over-Voltage Tolerance (OVT) on all Data Ports up to 6 V without External Components

Applications

- Cell Phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

Description

The FSA3051 is a 6 Ω, bi-directional, low-power, two-port, high-speed, Single Pole / Double Throw (SPDT) analog switch. It features an extremely low on capacitance (C_{ON}) of 7.7 pF and wide bandwidth of 1.0 GHz.

The FSA3051 contains special circuitry on the switch I/O pins for applications where the V_{CC} supply is powered-off (V_{CC}=0 V), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the select (S) pin is lower than the supply voltage (V_{CC}). This feature is especially valuable to ultra-portable applications, such as cell phones, allowing for direct interface with the general-purpose I/Os of the baseband processor. Other applications include switching in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSA3051TMX	NT	-40 to +85°C	6-Lead, Dual, Ultra-ultrathin Molded Leadless Package (TMLP), 1.0 x 1.0 mm. Top left unit orientation in carrier tape.
FSA3051TMX-F147	NT	-40 to +85°C	6-Lead, Dual, Ultra-ultrathin Molded Leadless Package (TMLP), 1.0 x 1.0 mm. Bottom left unit orientation in carrier tape.

MicroPak™ is a trademark of ON Semiconductor Corporation.

October-2017, Rev.2

Publication Order Number:
FSA3051/D

Analog Symbols

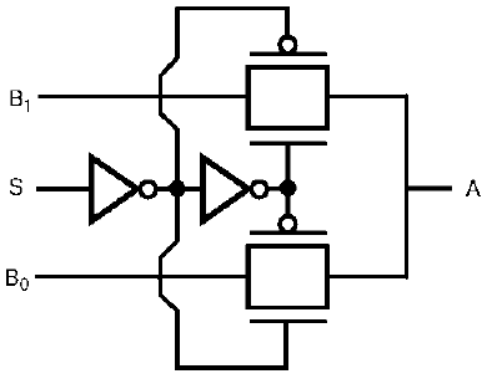


Figure 1. Logic Symbol

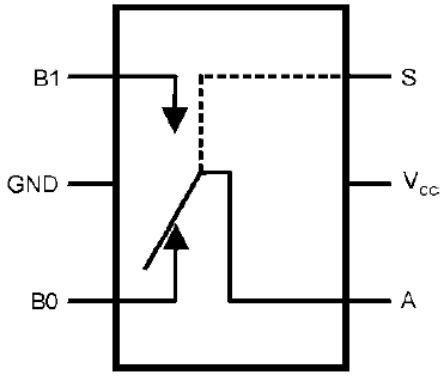


Figure 2. Analog Symbol

Pin Assignments

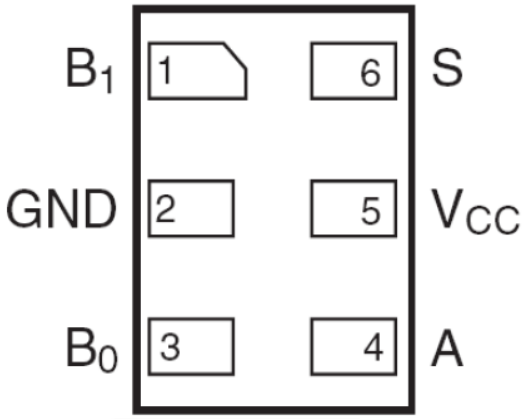


Figure 3. 6-Lead TMLP (Top-Through View)

Pin Definitions

UMLP Pin#	Name	Description
1	B_1	Data Port
2	GND	Ground
3	B_0	Data Port
4	A	Data Port
5	V_{CC}	Supply Voltage
6	S	Switch Select

Truth Table

S	Function
LOW	B_0 connected to A
HIGH	B_1 connected to A

Notes:
1. LOW $\leq V_{IL}$.
2. HIGH $\geq V_{IH}$.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V_{CC}	Supply Voltage		-0.5	6.0	V
V_{CNTRL}	DC Input Voltage[3]		-0.5	V_{CC}	V
V_{SW}	DC Switch I/O Voltage[3]		-0.50	6.00	V
I_{IK}	DC Input Diode Current		-50		mA
I_{OUT}	DC Output Current			50	mA
T_{STG}	Storage Temperature		-65	+150	°C
MSL	Moisture Sensitivity Level (JEDEC J-STD-020A)			1	Level
ESD	Human Body Model, ANSI/ESDA/JEDEC JS-001-2012	All Pins	2		kV
		I/O to GND	2		
		Power to GND	2		
	Charged Device Model, JEDEC: JESD22-C101		1		

Note:

3. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	1.6	5.5	V
V_{CNTRL}	Control Input Voltage (S)[4]	0	V_{CC}	V
V_{SW}	Switch I/O Voltage	-0.5	5.5	V
T_A	Operating Temperature	-40	+85	°C

Note:

4. The control input must be held HIGH or LOW and it must not float.

DC Electrical Characteristics

All typical value are at T_A=25°C unless otherwise specified.

Symbol	Parameter	Condition	V_{CC} (V)	T_A=- 40°C to +85°C			Unit
				Min.	Typ.	Max.	
V_{IK}	Clamp Diode Voltage	I_{IN}=-18 mA	3.0			-1.2	V
V_{IH}	Input Voltage High		1.8 to 4.3	1.3			V
			4.3 to 5.5	1.7			
V_{IL}	Input Voltage Low		1.8 to 4.3			0.5	V
			4.3 to 5.5			0.7	
I_{IN}	Control Input Leakage	V_{CNTRL}=0 to V_{CC}	1.8	-1		1	µA
			5.5	-1		1	
I_{OZ}	Off State Leakage	V_{SW}=0 V to V_{CC}	1.8	-2		2	µA
		V_{SW}=0 V to 3.6 V	5.5	-2		2	
I_{OFF}	Power-Off Leakage Current (All I/O Ports)	V_{SW}=0 V to 4.3 V, V_{CC}=0 V Figure 5	0	-2		2	µA
R_{ON}	Switch On Resistance(5)	V_{SW}=0.4 V, I_{ON}=-8 mA Figure 4	3.0		4	10	Ω
		V_{SW}=1.8 V, I_{ON}=-8 mA Figure 4	3.0		6	10	
R_{ON}	Switch On Resistance(5)	V_{SW}=0.4 V, I_{ON}=-8 mA Figure 4	1.8		6	10	Ω
		V_{SW}=1.8 V, I_{ON}=-8 mA Figure 4	1.8		14	25	
ΔR_{ON}	On Resistance Match Between Channels(5,6)	V_{SW}=0.4 V, I_{ON} = -8 mA	3.0		35		mΩ
			1.8		40		
I_{CC}	Quiescent Supply Current	V_{CNTRL}=0 or V_{CC}, I_{OUT}=0	5.5			1	µA
I_{CCT}	Increase in I_{CC} Current per Control Voltage and V_{CC}	V_{CNTRL}=1.8 V	3.0			10	µA
		V_{CNTRL}=2.6 V	5.5			10	
		V_{CNTRL}=1.8 V	5.5			15	

Notes:

5. Measured by the voltage drop between A and Bn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (A or Bn ports).
6. ΔR_{ON} = R_{ON} maximum - R_{ON} minimum measured at identical V_{CC}, temperature, and voltage levels.
7. Guaranteed by characterization.

AC Electrical Characteristics[8]

All typical value are for V_{CC}=3.3 V at T_A=25°C unless otherwise specified.

Symbol	Parameter	Condition	V_{CC} (V)	T_A=- 40°C to +85°C			Unit
				Min.	Typ.	Max.	
t_{ON}	Turn-On Time S to Output	R_L=50 Ω, C_L=5 pF, V_{SW}=0.8 V, Figure 6, Figure 7	3.0 to 3.6		34		ns
			1.8		110		
t_{OFF}	Turn-Off Time S to Output	R_L=50 Ω, C_L=5 pF, V_{SW}=0.8 V, Figure 6, Figure 7	3.0 to 3.6		23		ns
			1.8		50		
t_{PD}	Propagation Delay	C_L=5 pF, R_L=50 Ω, Figure 6, Figure 8	3.3		0.2		ns
			1.8		0.3		
t_{BBM}	Break-Before-Make	R_L=50 Ω, C_L=5 pF, V_{SW1}=V_{SW2}=0.8 V, Figure 9	3.0 to 3.6	15		50	ns
			1.8			100	
O_{IRR}	Off Isolation	R_L=50 Ω, f=240 MHz, Figure 11	1.8		-20		dB
			3.0 to 3.6		-23		
Xtalk	Crosstalk	R_L=50 Ω, f=240 MHz, Figure 12	1.8		-18		dB
			3.0 to 3.6		-23		dB
BW	-3 db Bandwidth	R_L=50 Ω, C_L=0 pF, V_{SW}=0.4 V	1.8		810		MHz
		R_L=50 Ω, C_L=0 pF, Figure 10	3.0 to 3.6		1		GHz
		R_L=50 Ω, C_L=5 pF, Figure 10			750		MHz

Note:
8. Guaranteed by characterization. Not production tested.

Capacitance [9]

Symbol	Parameter	Condition	V_{CC} (V)	T_A=- 40°C to +85°C			Unit
				Min.	Typ.	Max.	
C_{IN}	Control Pin Input Capacitance		0		1.5		pF
C_{ON}	A Port On Capacitance	f=1 MHz,	3.0		7.7		
		f=240 MHz, Figure 14	3.3		7.7		
		f=1 MHz,	1.8		10.0		
		f=240 MHz, Figure 14	1.8		5.0		
C_{OFF}	Bn Port Off Capacitance	f=1 MHz	3.0		3.3		
		f=240 MHz, Figure 13	3.3		3.3		
		f=1 MHz	1.8		5.0		
		f=240 MHz, Figure 13	1.8		4.0		

Note:
9. Not production tested.

Test Diagrams

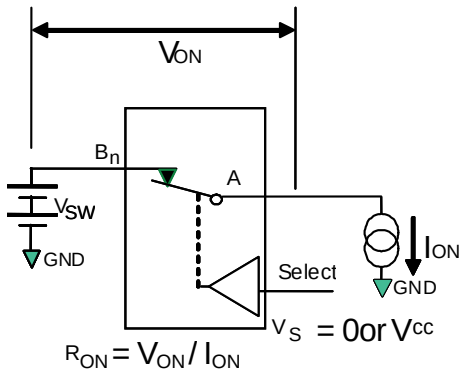
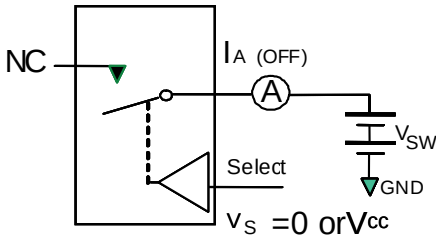
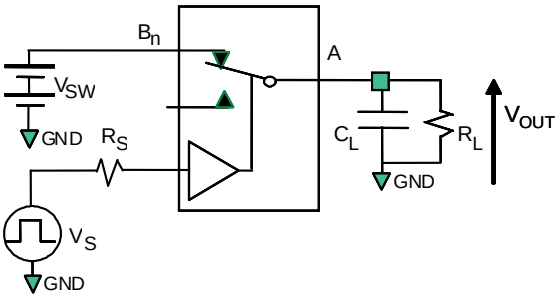


Figure 4. On Resistance



**Each switch port is tested separately

Figure 5. Off Leakage



R_L, R_S, and C_L are functions of the application environment (see AC Tables for specific values)
C_L includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load

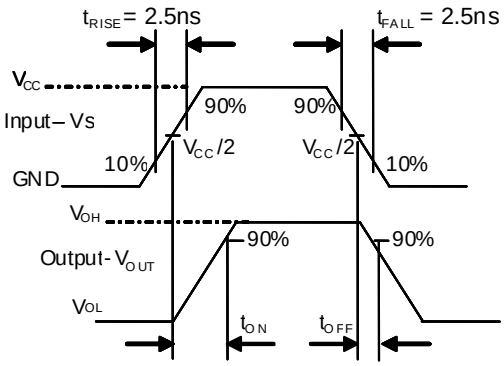


Figure 7. Turn-On / Turn-Off Waveforms

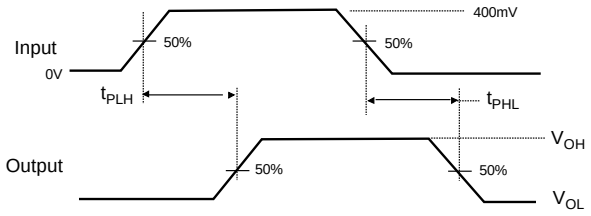
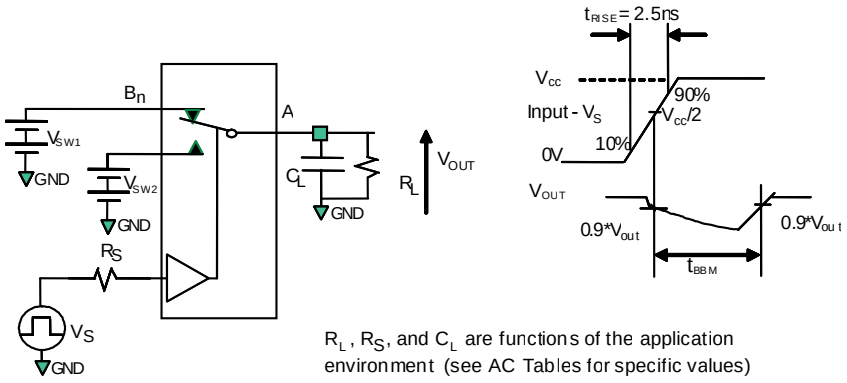


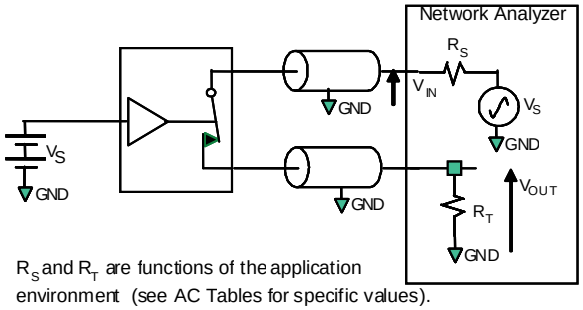
Figure 8. Propagation Delay ($t_R t_F$ – 500 ps)

Test Diagrams (Continued)



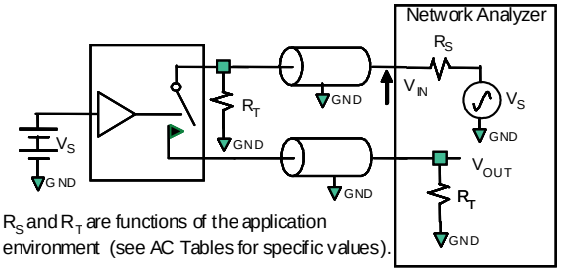
R_L, R_S, and C_L are functions of the application environment (see AC Tables for specific values)
C_L includes test fixture and stray capacitance.

Figure 9. Break-Before-Make Interval Timing



R_S and R_T are functions of the application environment (see AC Tables for specific values).

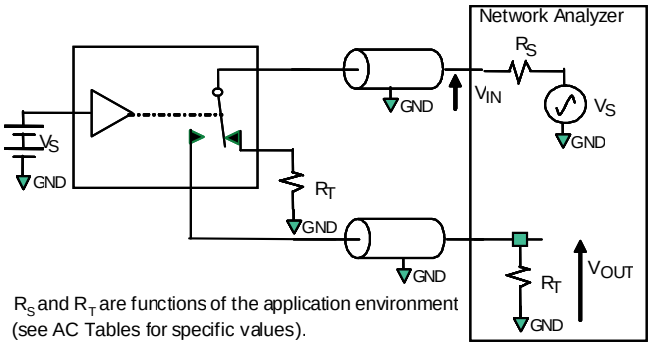
Figure 10. Bandwidth



R_S and R_T are functions of the application environment (see AC Tables for specific values).

Off isolation = 20 Log (V_{OUT} / V_{IN})

Figure 11. Channel Off Isolation



R_S and R_T are functions of the application environment (see AC Tables for specific values).

Crosstalk = 20 Log (V_{OUT} / V_I)

Figure 12. Channel-to-Channel Crosstalk

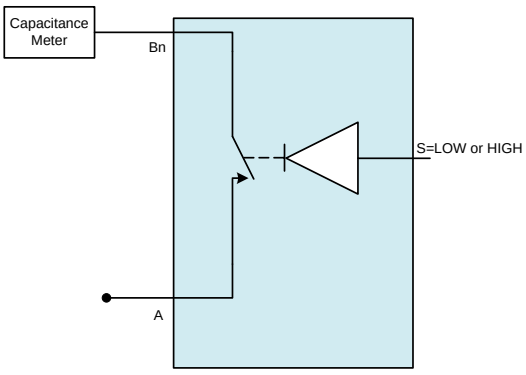


Figure 13. Channel Off Capacitance

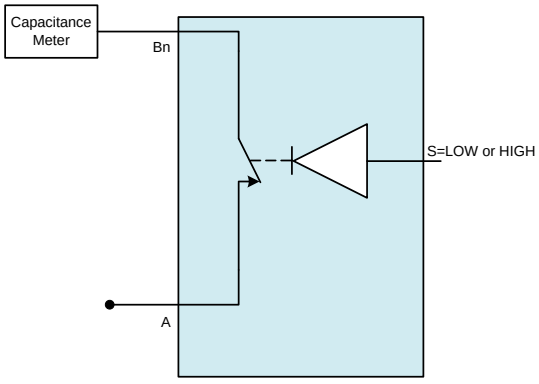


Figure 14. Channel On Capacitance

Carrier Tape Orientation

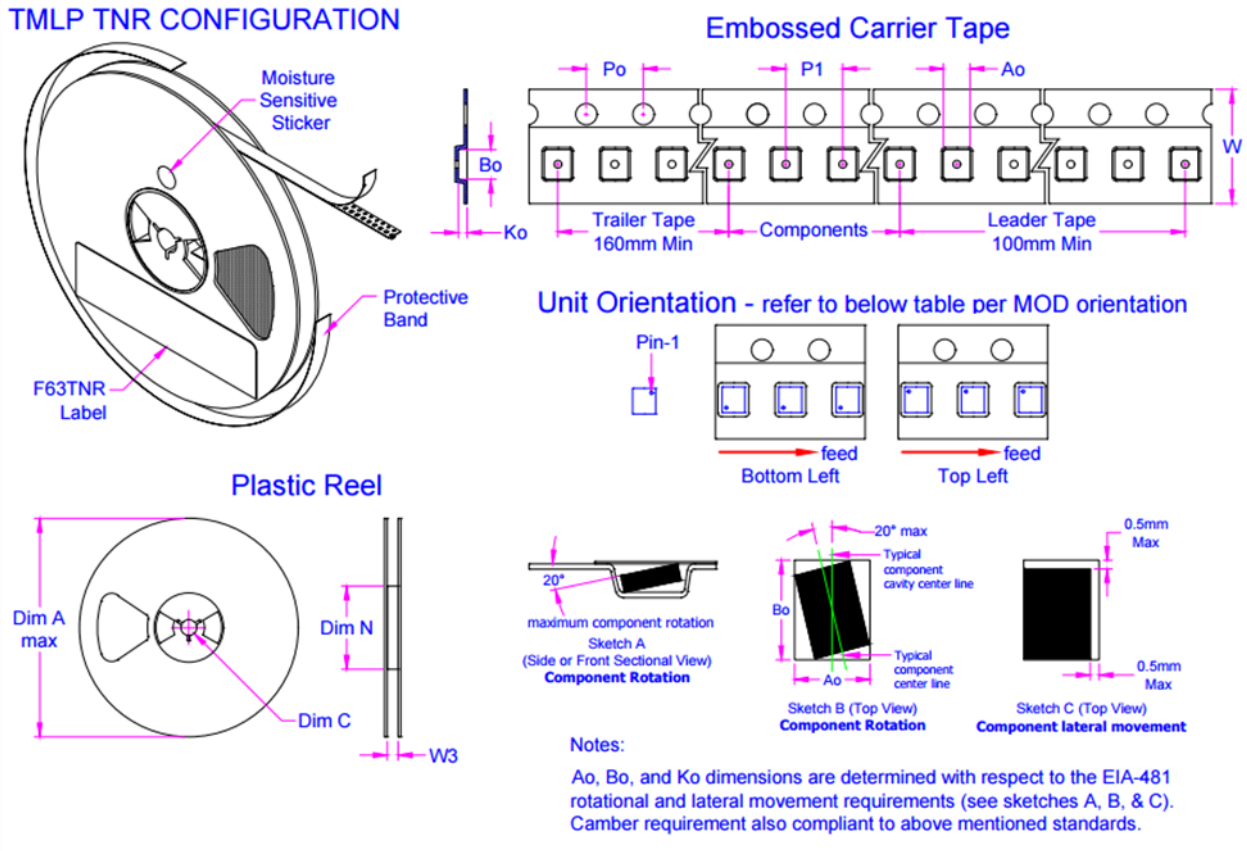
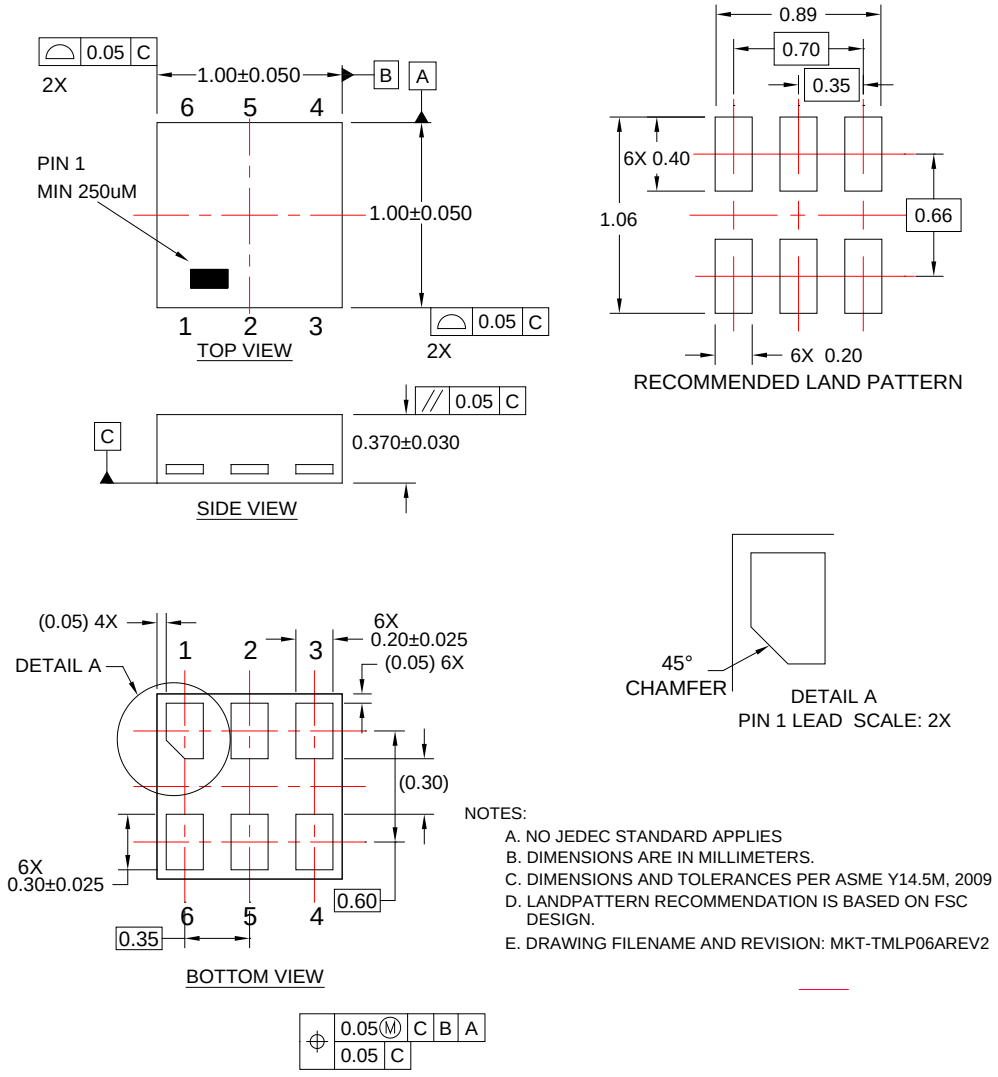


Figure 15. TMLP Carrier Tape Packing

Part Number	Unit Orientation
FSA3051TMX	Top Left
FSA3051TMX-F147	Bottom Left

Physical Dimensions



NOTES:

A. NO JEDEC STANDARD APPLIES
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009
D. LANDPATTERN RECOMMENDATION IS BASED ON FSC DESIGN.
E. DRAWING FILENAME AND REVISION: MKT-TMLP06AREV2

6-Lead, Dual, Ultra-ultrathin Molded Leadless Package (TMLP), 1.0 x 1.0 mm

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
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